

34. (New) The method of Claim 33, wherein said wafer is a silicon substrate wafer, and said forming a peripheral break trench structure includes etching the silicon substrate wafer with a TMAH (Tetra Methyl Ammonium Hydroxide) wet etch process.

35. (New) A fluid ejection device produced by the method of Claim 33.

REMARKS

Entry of the foregoing amendments is respectfully requested.

It is noted that the transmittal letter for the continuation application included a request to amend the specification to include the continuing application data set out above. This amendment is included herein to comply with the revised amendment practice which became effective on July 30, 2003.

Respectfully submitted,



Larry K. Roberts
Registration No. 28,464

Dated: 11/5/03

Law Offices of Larry K. Roberts, Inc.
P.O. Box 8569
Newport Beach, CA 92658-8569
Telephone (949) 640-6200
Facsimile (949) 640-1206